

XLED

xLED-LUME-4568 Pin Fin Heat Sink Φ60mm for Lumens

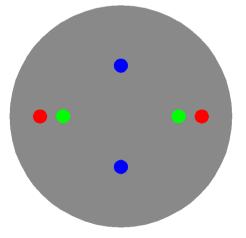
Features VS Benefits

- * The xLED-LUME-4568 Lumens Pin Fin LED Heat Sinks are specifically designed for luminaires using the Lumens LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 300 to 1,400 lumen.
- * Thermal resistance range Rth 4.76°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Lumens Ergon COB series, and AC-ALL series LED engines.
- * Diameter 45.0mm standard height 68.0mm Other heights on request.
- * Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Lumens COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.





Lumens LED Modules directly Mounting Options Lumens Ergon COB_HO, COB_HO+, COB_HE Series :

ERC1812xxxxHE; ERC1820xxxxHE:

With the Zhaga Book 3 holders for the red indicator marks.

Lumens Ergon COB_HO, COB_HO+, COB_HE Series :

ERC1507xxxxHE;

Direct mounting with machine screws M3x6.5mm

Lumens AC-ALL Series :

EDC/47C/10W/xxx/120V/B; EDC/47C/10W/xxx/230V/A; EDC/47C/12W/xxx/230V/A; EDC/47C/12W/xxx/120V/B;

Direct mounting with machine screws M3x6.5mm

Please refer to the www.lumensleds.com data provided on the manual.

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Mounting Options and Drawings & Dimensions

Example:xLED-LUME-4568-B-1,2

Example:xLED-LUME-45 1 - 2

1 Height (mm)

Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

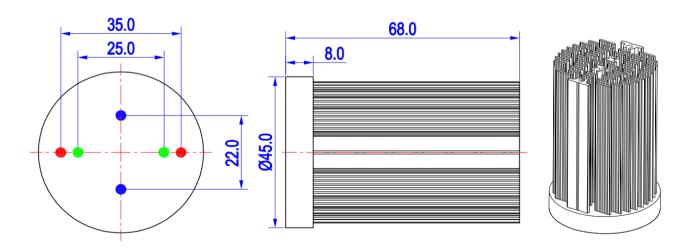
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	Ergon COB (15.85×15.85)	/	М3	6.5mm	22.0mm/ 2-@180°
2	Ergon COB (17.85×17.85)	/		6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
	Ergon COB (15.85×15.85)	BJB Holder 47.319.6104.50	МЗ		
		ldeal Holder 50-2001CR			
3	AC-ALL Series	Lumens		6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
	Ergon COB (17.85×17.85)	BJB Holder 47.319.2131.50	М3		
		ldeal Holder 50-2101CR			

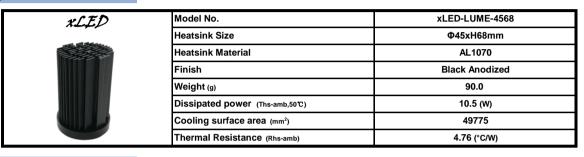


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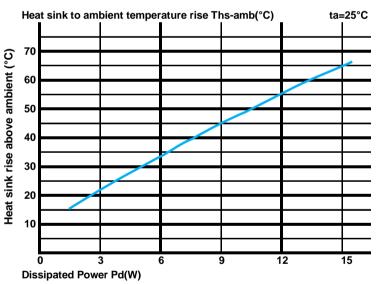
The product deta table



The thermal data table

- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (1 \eta L)$.
 - Pd Dissipated power; Pe Electrical power; $\eta L = \text{Light effciency of the LED module}$;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		xLED-LUME-4568		
Dissipated Power Pd(W)	3.0	7.00	21.0	
	6.0	5.50	33.0	
	9.0	5.00	45.0	
	12.0	4.58	55.0	
	15.0	4.27	64.0	



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.
- T_{junctio}
 R_{junction-case}
 T_{case}
 75°C
 R_{interface (TIM)}
 R_{heatsink-ambient}
 T_{ambient}
 25°C
- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- $\theta\,$ Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface}}(TIM)$ [°C/W], the thermal resistance with the heat sink is $R_{\text{heatsink-ambient}}$ [°C/W], and the ambient temperature is T_{ambient} [°C].
- *Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction} = (R_{junction-case} + R_{case-ambient}) Pd + T_{ambient}$

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